

81  
1. (Twice Amended) A printed circuit board unit comprising:  
a printed circuit board;  
an electronic component;  
a solder bump interposed between the printed circuit board and the electronic component so  
as to fix the electronic component to the printed circuit board; and  
an insulated film disposed between the printed circuit board, not adhered thereto, and the  
electronic component so as to define a through hole for receiving the solder bump, wherein  
the through hole is designed to form a constriction in the solder bump between the printed  
circuit board and the electronic component.

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8. (Amended) The printed circuit board unit according to claim 1, wherein an inner surface  
of the through hole is covered with a coating wet to the solder bump.